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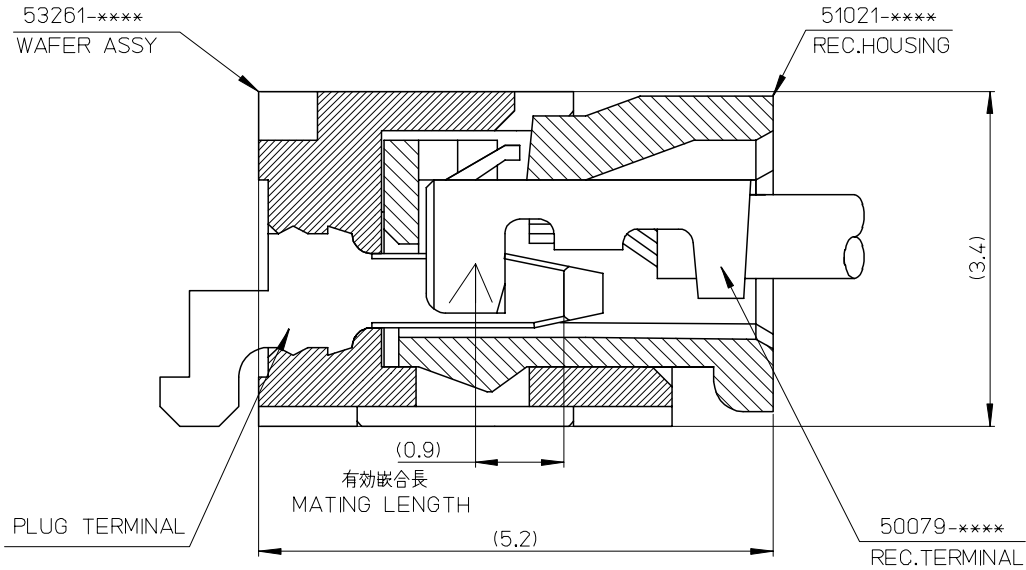
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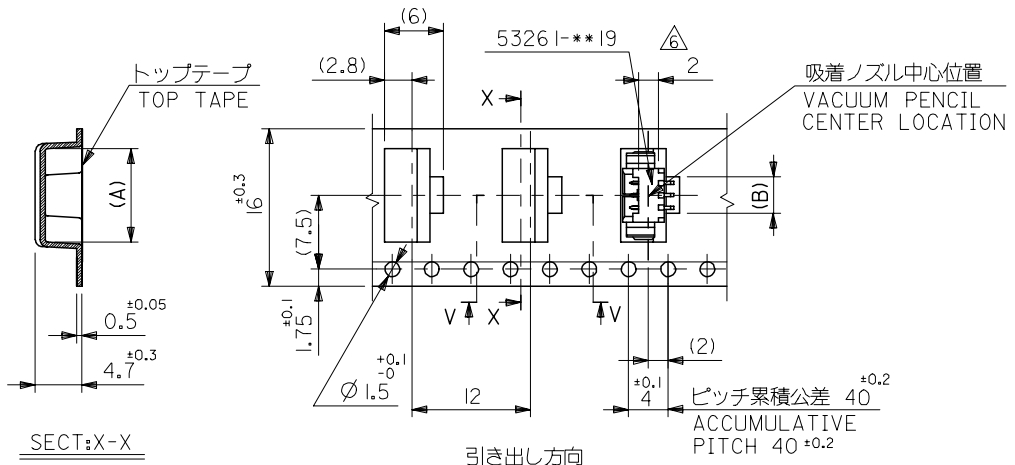
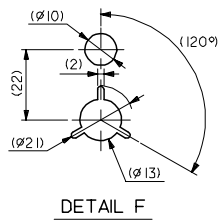
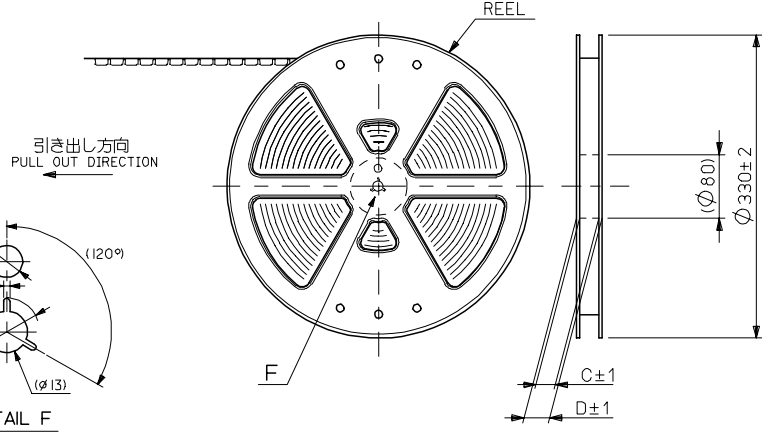
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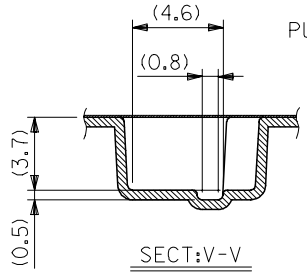


53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION				
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED				
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-51021-002	SHEET NO. 1 OF 1	
	ANGULAR	± --- °	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS									



SECT:X-X



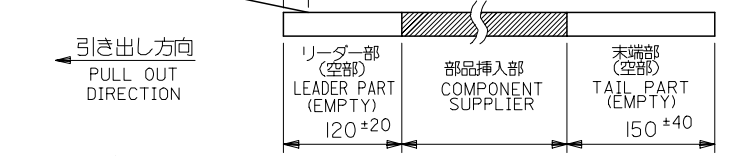
SECT:V-V

注記 NOTES

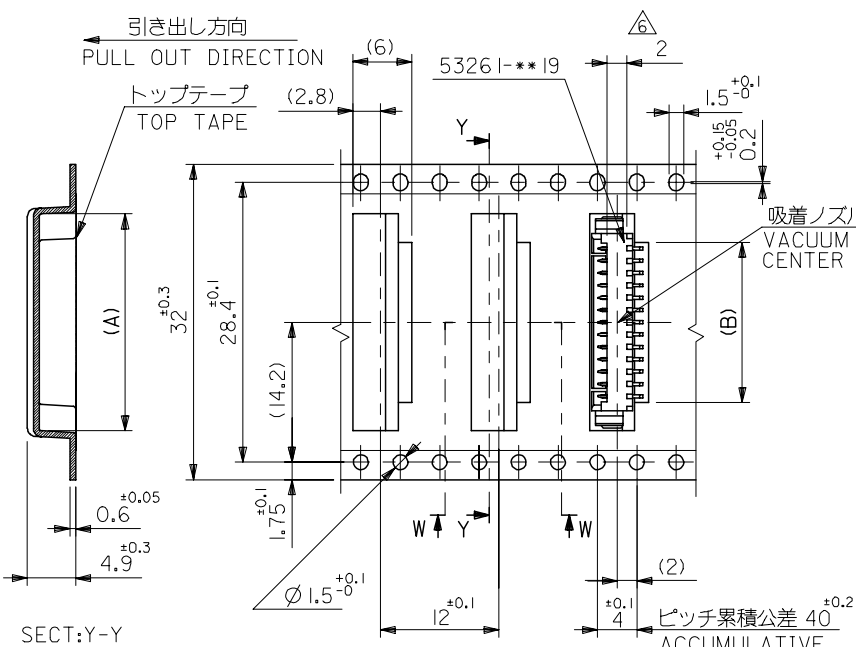
- 5326 I-**-19 の詳細寸法については図面 SD-53261-024 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53261-024
- 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

トップテープリーダー部 TOP TAPE LEADER PART	トップテープ未接着部 TOP TAPE NON-BONDED PART
175 ±25	25 ±5
- トップテープの剥離強度: 0.1~1.3N(10~130gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE: 0.1~1.3N(10~130gf) (PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)

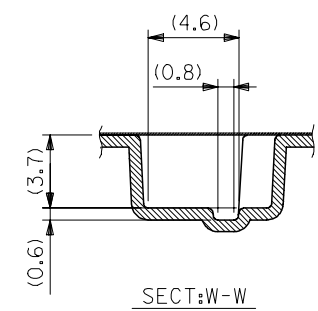
<剥離速度: 300mm/min (参考)>
PEELING SPEED: 300mm/min. (REFERENCE)
- 材料 (MATERIAL)
 キャリアテープ(CARRIER TAPE): ポリプロピレン(POLYPROPYLENE)
 トップテープ (TOP TAPE): PET ,PE ,PEF
 リール (REEL): ポリスチレン (PS) <リサイクル材含む>
 POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>
- △ コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA
- 本製品は 53261-**-90 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-90



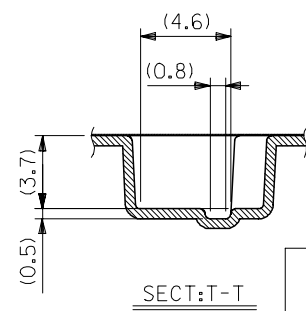
MODEL NO.	53261-**-71	16	21.4	17.4	3.7	9.5	53261-0371	3
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	2.45	8.25	53261-0271	2
GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
10 UNDER ±0.2	DRAWN BY DATE H. SHIMABUKUR '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG -LEAD FREE-					
10 OVER 30 UNDER ±0.25	CHECKED BY DATE K. TOJO '04/02/06		MOLEX MOLEX INCORPORATED					
30 OVER ±0.3	APPROVED BY DATE M. SASAO '04/02/06		DOCUMENT NO. SD-53261-023					
ANGULAR ±3 °	MATERIAL NO.		SHEET NO. 1 OF 3				SIZE A3	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



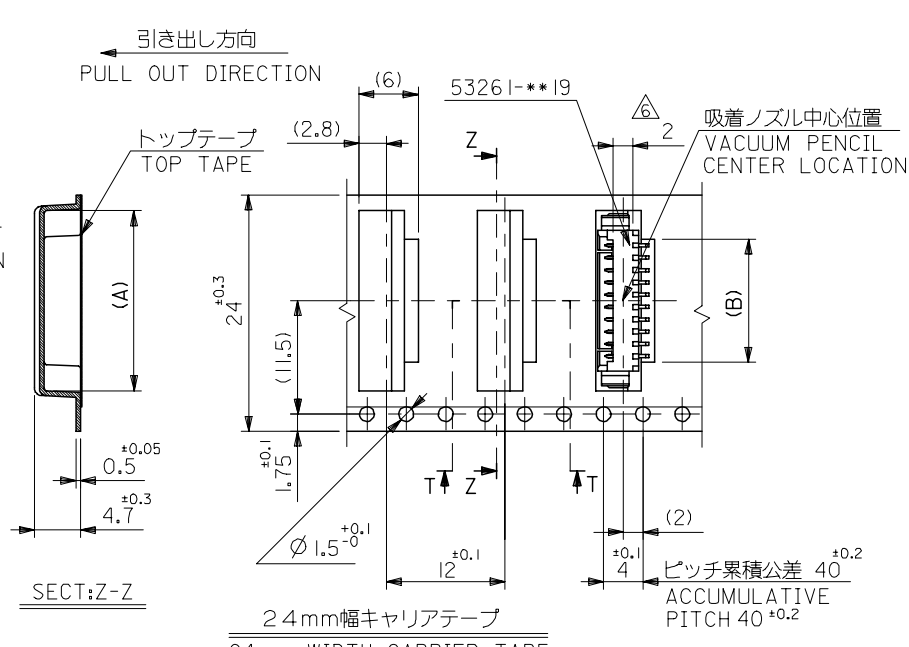
32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE



SECT:W-W



SECT:T-T



24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
24	29.4	25.4	13.7	19.5	-1171	11
			12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
4.95	10.75	53261-0471	4			

MODEL NO.	53261-**71	キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL. NO.	極数 CKT.
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS		THIRD ANGLE PROJECTION	
10 UNDER ±0.2		MM ONLY		---	METRIC			
10 OVER 30 UNDER ±0.25		DRAWN BY DATE		TITLE				
30 OVER ±0.3		H. SHIMABUKUR '04/02/06		1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG -LEAD FREE-				
ANGULAR ±3 °		CHECKED BY DATE		MOLEX INCORPORATED				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		K. TOJO '04/02/06		MATERIAL NO.		DOCUMENT NO.		SHEET NO.
		APPROVED BY DATE		SEE CHART		SD-53261-023		2 OF 3
		M. SASAO '04/02/06		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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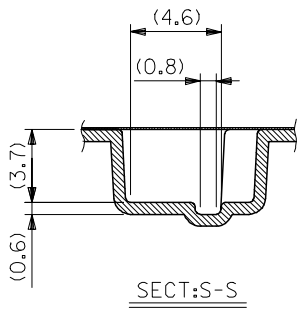
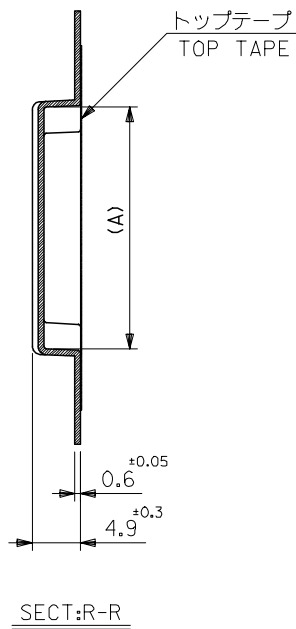
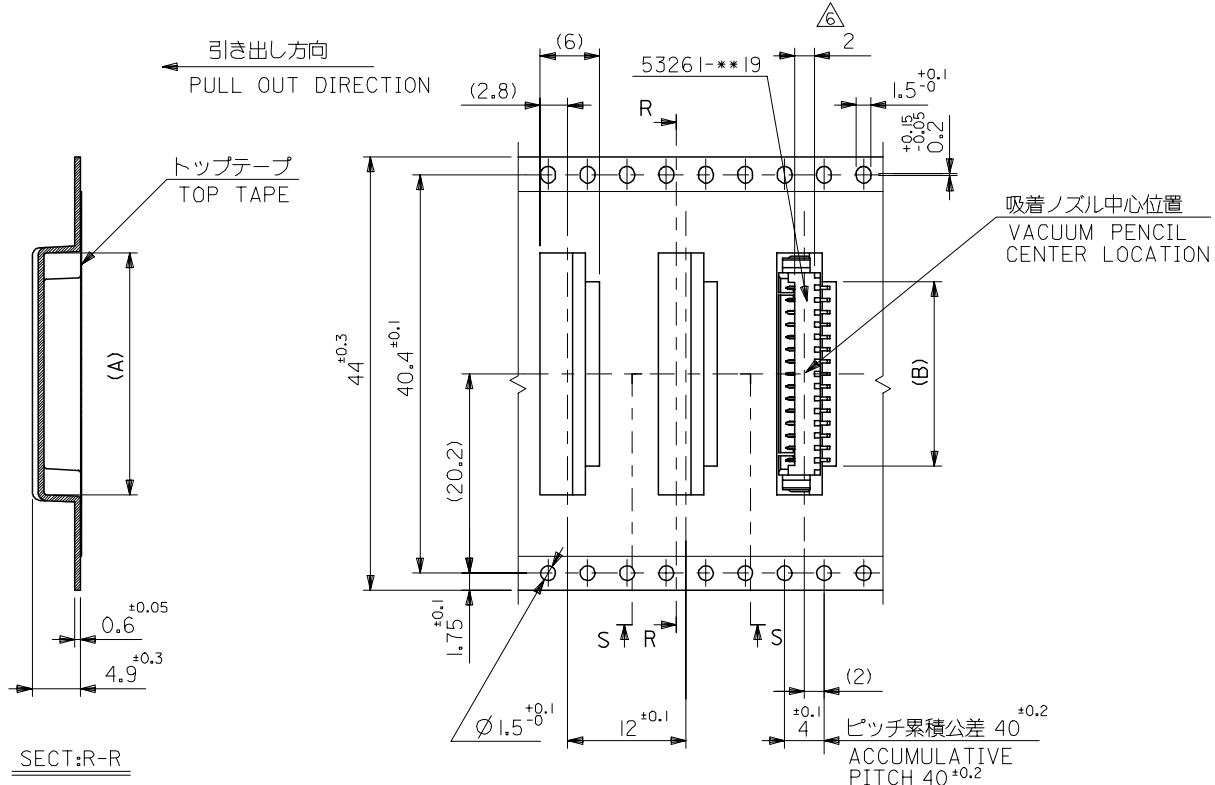
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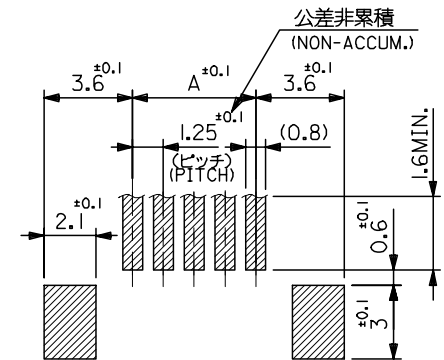
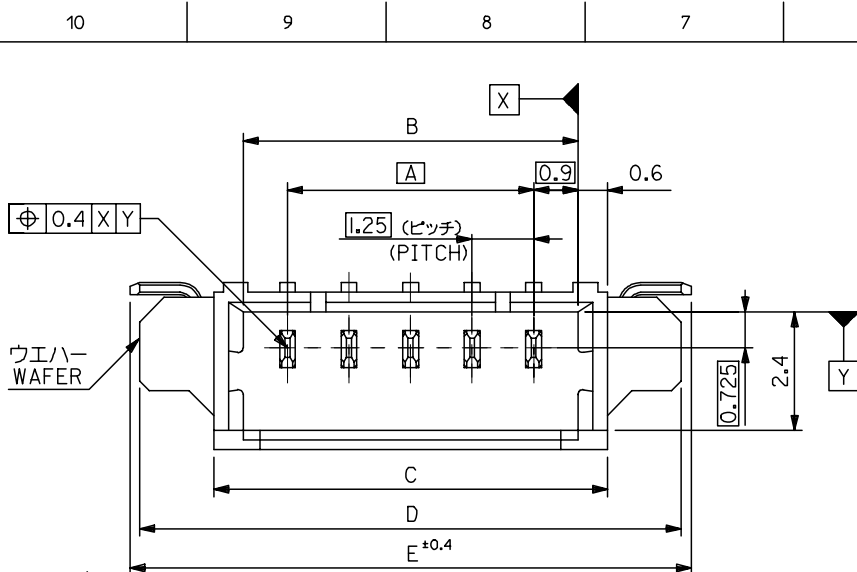
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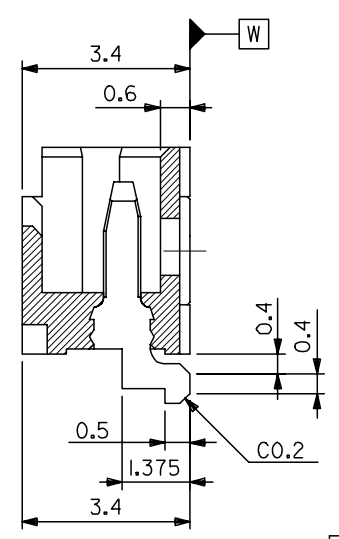
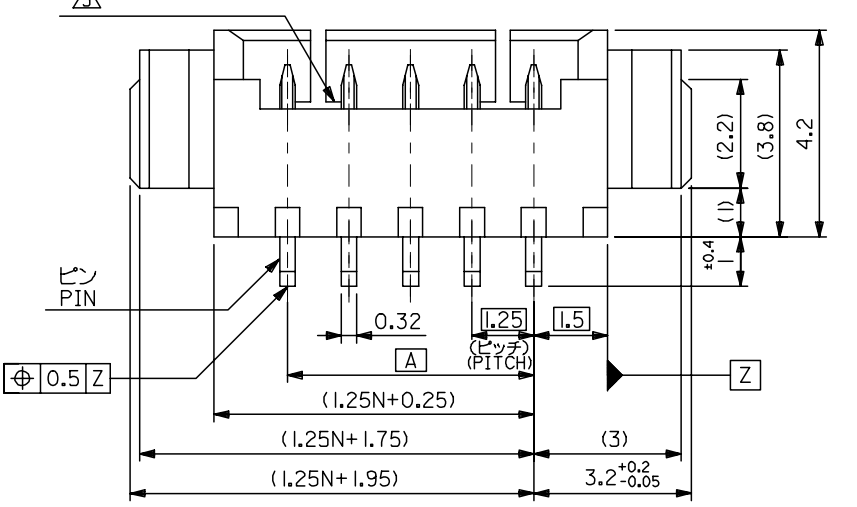


44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE

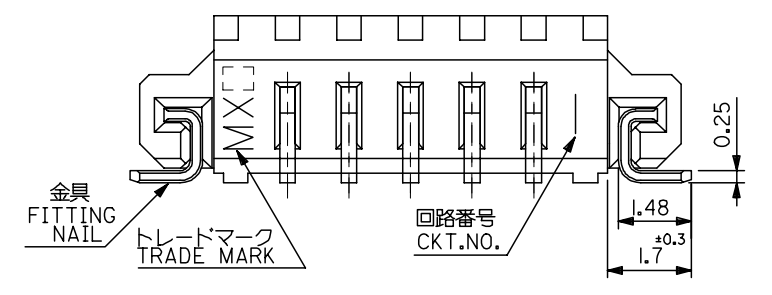
MODEL NO. 53261-**-71		キャリアテープ幅 CARRIER TAPE WIDTH	44	49.4	45.4	21.2	27.0	53261-1771	17
						18.7	24.5	53261-1571	15
						17.45	23.25	53261-1471	14
								MATERIAL. NO.	極数 CKT.
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
10 UNDER ±0.2		DRAWN BY DATE H. SHIMABUKUR '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG -LEAD FREE-					
10 OVER 30 UNDER ±0.25		CHECKED BY DATE K. TOJO '04/02/06		APPROVED BY DATE M. SASAO '04/02/06					
30 OVER ±0.3		APPROVED BY DATE M. SASAO '04/02/06		MATERIAL NO. DOCUMENT NO. SHEET NO. SEE CHART SD-53261-023 3 OF 3					
ANGULAR ±3 °		MATERIAL NO. DOCUMENT NO. SHEET NO. SEE CHART SD-53261-023 3 OF 3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3							



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)
(SCALE 5:1)



[断面図]
[CROSS SECTION]



注記 NOTES

1. 嵌合相手: 51021 シリウス
MATES WITH: 51021 SERIES
2. 材質 MATERIAL
ウエハー: NYLON46, UL94V-0
ピン: リン青銅
PIN: PHOS-BRO
: 銅メッキ 1.0 マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0 マイクロメートル以上
: NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
金具
FITTING NAIL: リン青銅
: PHOS-BRO
: 銅メッキ 1.0 マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0 マイクロメートル以上
: NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
- △ ロック窓は2, 3極は1箇所, 4極以上は2箇所とする。
LOCKING WINDOW:
ONE PLACE FOR 2 AND 3 CKT. AND
TWO PLACES FOR MORE THAN 3 CKT.
4. ソルダテール部のスレ量及び金具(補強板)のスレ量は基準面[W]に対し、上方向0.05 MAX.、下方向に0.1 MAX.とする。[W] OFFSET BETWEEN BASIS PLANE TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:
UPPER SIDE: 0.05MAX.
LOWER SIDE: 0.1MAX.
5. 本製品は 53261-**-10 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-10

26.4	26	23	21.8	20	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	-1519	15	
22.65	22.25	19.25	18.05	16.25	-1419	14	
21.4	21	18	16.8	15	-1319	13	
20.15	19.75	16.75	15.55	13.75	-1219	12	
18.9	18.5	15.5	14.3	12.5	-1119	11	
17.65	17.25	14.25	13.05	11.25	-1019	10	
16.4	16	13	11.8	10	-0919	9	
15.15	14.75	11.75	10.55	8.75	-0819	8	
13.9	13.5	10.5	9.3	7.5	-0719	7	
12.65	12.25	9.25	8.05	6.25	-0619	6	
11.4	11	8	6.8	5	-0519	5	
10.15	9.75	6.75	5.55	3.75	-0419	4	
8.9	8.5	5.5	4.3	2.5	-0319	3	
53261-**-19	7.65	7.25	4.25	3.05	1.25	53261-0219	2

MODEL NO.	E	D	C	B	A	MATERIAL. NO.	極数 CKT.
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REVISED EC NO: J2005-3130 DRW:NDA 2005/04/19 CHK:KTOYODA 2005/04/21 APPR:NUKITA 2005/04/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABU	DATE 04/02/06	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 04/02/06	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/06	DOCUMENT NO. SD-53261-024		
	ANGULAR	±3 °	MATERIAL NO. SEE DRAWING		SHEET NO. 1 OF 1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					